



## INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

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| <b>(21) International Application Number:</b> PCT/US99/13738<br><b>(22) International Filing Date:</b> 17 June 1999 (17.06.99)<br><br><b>(30) Priority Data:</b><br>60/090,295           23 June 1998 (23.06.98)       US<br>60/092,170           9 July 1998 (09.07.98)       US<br>09/232,936           19 January 1999 (19.01.99)   US<br><br><b>(71) Applicant (for all designated States except US):</b> AMERASIA INTERNATIONAL TECHNOLOGY, INC. [US/US]; 70 Washington Road, Princeton Junction, NJ 08550 (US).<br><br><b>(72) Inventor; and</b><br><b>(75) Inventor/Applicant (for US only):</b> CHUNG, Kevin, Kwong-Tai [US/US]; 522 Brickhouse Road, Princeton, NJ 08540 (US).<br><br><b>(74) Agents:</b> BERARD, Clement, A. et al.; Dann, Dorfman, Herrell & Skillman, P.C., Suite 720, 1601 Market Street, Philadelphia, PA 19103 (US). | <b>(81) Designated States:</b> CN, JP, KR, SG, US, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).<br><br><b>Published</b><br><i>With international search report.</i><br><i>Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i> |                                                                                                                                             |

**(54) Title:** METHOD OF MAKING AN ADHESIVE PREFORM LID FOR ELECTRONIC DEVICES**(57) Abstract**

An electronic device (22) is enclosed within a package or module (10) having a lid (40) that is sealed with an adhesive preform (30) that has been pre-applied onto the bonding areas of the lid (40). The adhesive preforms (30) are formed of a wet adhesive deposited on a release substrate (32) as a preform in predetermined locations with respect to a set of reference guide holes (34, 36) so as to facilitate subsequent attachment to lids (40) with pick-and-place equipment or a guide plate. The wet adhesive preforms (30) are B-staged or dried to form dry solid adhesive preforms (30).

Both the lids (40) and the adhesive preforms (30) may be formed of electrically insulating or electrically conducting materials. In use, the lids (40) and adhesive preforms (30) are attached to enclose the electronic device (22) by bonding the adhesive preforms (30) at temperatures that are substantially lower than those at which the soldering of conventional lids is typically performed.

